

Development of the PICosecond subMICrometer (PICMIC) detector

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on behalf of the PICMIC collaboration

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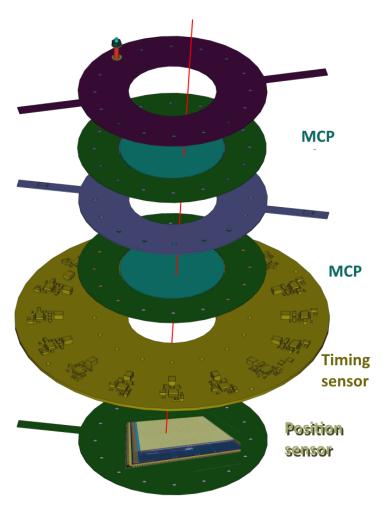




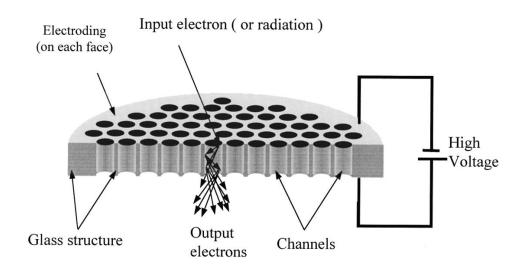
Outline

- ☐ PICMIC concept
 - Time measurement
 - Position measurement
- ☐ Detail of the position sensor prototype
 - Layout of 3D view
 - Architecture
- **☐** Experimental results
 - Threshold S-curves
 - Position measurement of injection probe
 - Test with α and γ sources
- ☐ Ongoing R&D
 - Large area position sensor PICMIC-1
 - ❖ PICMIC with Nano-Channel Plate (NCP)
- **☐** Summary

PICMIC concept

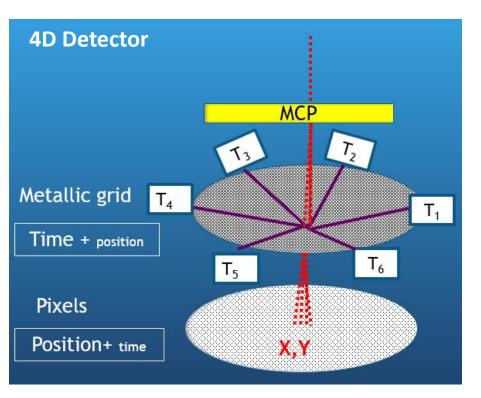


- MCP is as for now is one of the best timing devices with a few picoseconds of resolution.
- * MCP has an excellent intrinsic spatial resolution since the avalanche produced by the incoming particle is constrained to one of the glass tube whose diameter can ban as small as a couple of μm.
- MCP are often used for their timing while their spatial resolution is not appropriately exploited.



PICMIC concept

- □ To fully exploit MCP a new scheme is proposed
 - ❖ A transparent grid placed downstream the MCPs and read out by sensors with excellent time resolution.
 - A detection matrix with small pixels to measure the position of the avalanche while requiring limited number of electronics channels.

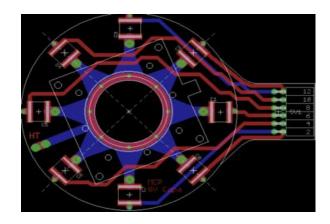


Concept description

- ☐ The avalanche crosses a transparent grid connected on its periphery to a few timing sensors.
- ☐ The avalanche is then collected by pixels.
- 1. Measure X,Y, by the fired woven strips
- 2. Measure T_i by time sensors
- Subtract time propagation using speed propagation
- 4. Average value on the (T_i-T_{i(propag)})

$$\mathsf{T}_{\mathsf{abs}} = \frac{\sum_{1}^{N} (T_i - T_{i(propag)})}{N}$$

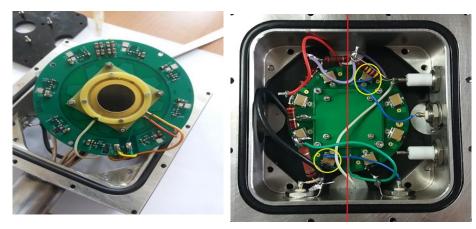
Time measurement



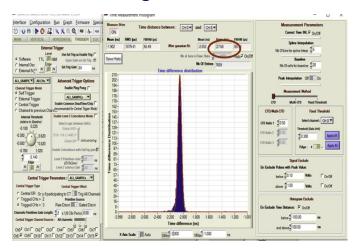
8-point PCB for the time measurement. PCB to be in contact with the grid



SAMPIC: TDC ASIC allowing to reach 3 ps time resolution



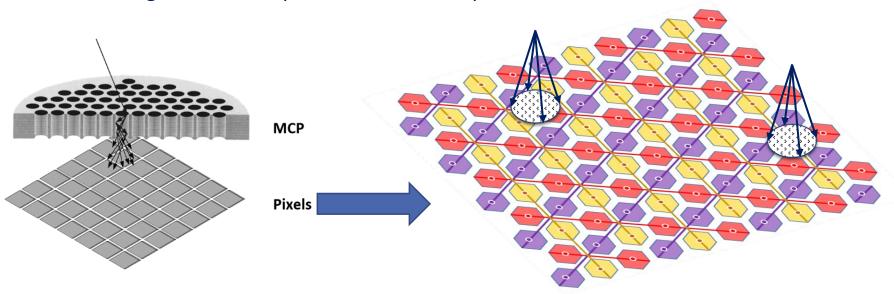
System tested on 2-MCP system of 25mm diameter using α source



Time resolution of arrival time of two channels is of 30 ps \rightarrow 10 ps by exploiting 8 channels

Position measurement

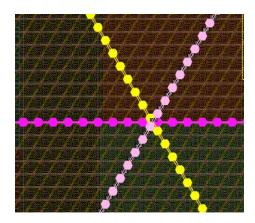
- □ To reach few microns resolution with a limited number of electronic channels, a new concept was developed.
 - Connect the pixels in woven strips
 - Two neighboring pixels are connected to two different strips
 - Each strip is connected to one electronic channel
 - Share the charge among a few ones
 - Crossing the fired strip to determine the position

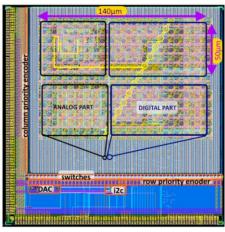


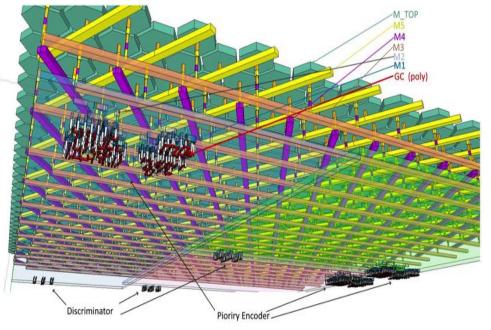
 $N \times N \rightarrow 3N$: Reduction of electronic channels, power consumption and occupancy

Position sensor prototype: PICMIC-0

- Although there is no silicon sensor, the CMOS technology was used.
- ☐ Pixels, the interconnections as well as the readout electronics are implemented in TJ 180 nm (6 metal layers) technology.

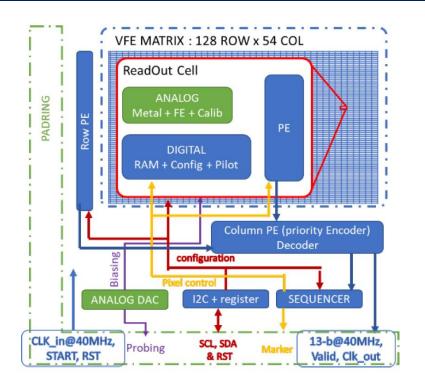




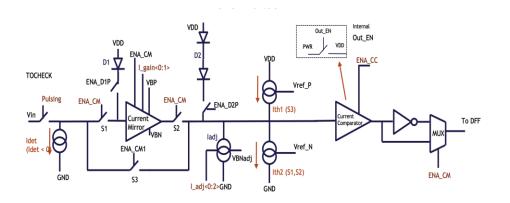


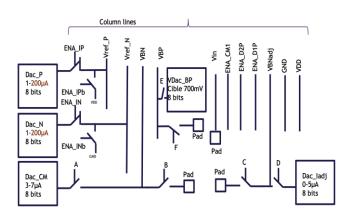
| Parameters | Value | |
|-------------------------------|----------------------------------------------------------|--|
| Design Flow | Cadence DoT flow | |
| Technology | TJ CIS 180nm | |
| Power supplies | 1.8V | |
| Power density | >172mW/cm ² | |
| Die dimension | ~7.5x7.5 mm ² (6.5x7.5mm ² active) | |
| Anode dimension | ~22µ²(5µm hexagonal pitch) | |
| Readout pixel dimension | 50μmx140μm | |
| Readout matrix | 128x54 cells (only 2556 active) | |
| Input clock | 40MHz | |
| Read-out port | 13-bit parallel, 1 sync clock out, 1 marker | |
| I/O Pad | CMOS | |
| Slow control | I ² C | |
| Max data rate (1Mhz hit rate) | 390Mbps | |

Position sensor prototype: PICMIC-0



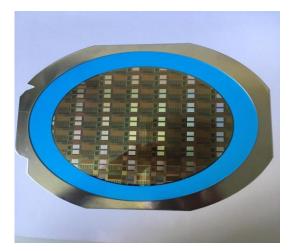
- Current conveyor preamp followed by a comparator. They are optimized to cover the dynamic range of a single and a doublet MCP.
- 5 DACs are used to control the preamp and the comparator response globally.
- ☐ One DAC (3-bit) to correct the threshold of each cell individually.
- ☐ Priority encoder protocol is used to read out only the cells with data.



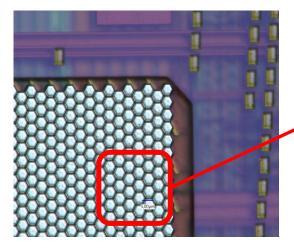


Position sensor prototype: PICMIC-0

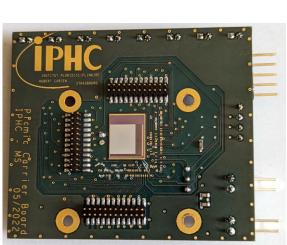
Prototype chip and test bench



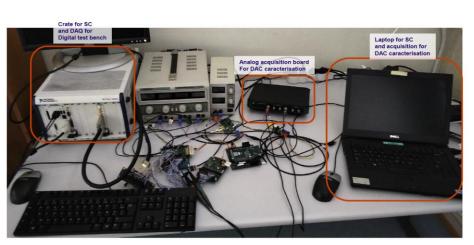
TJ wafer



Hexagonal pixels



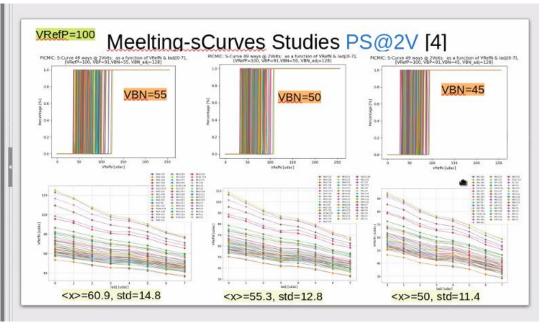
Test board



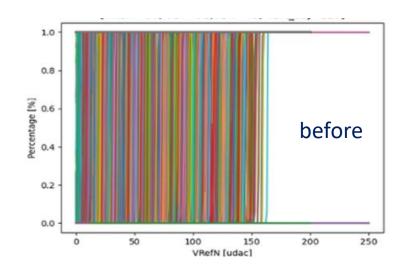
5,00µm

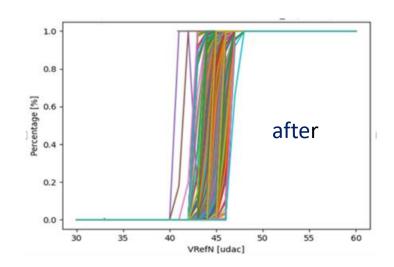
Test bench

Position sensor test



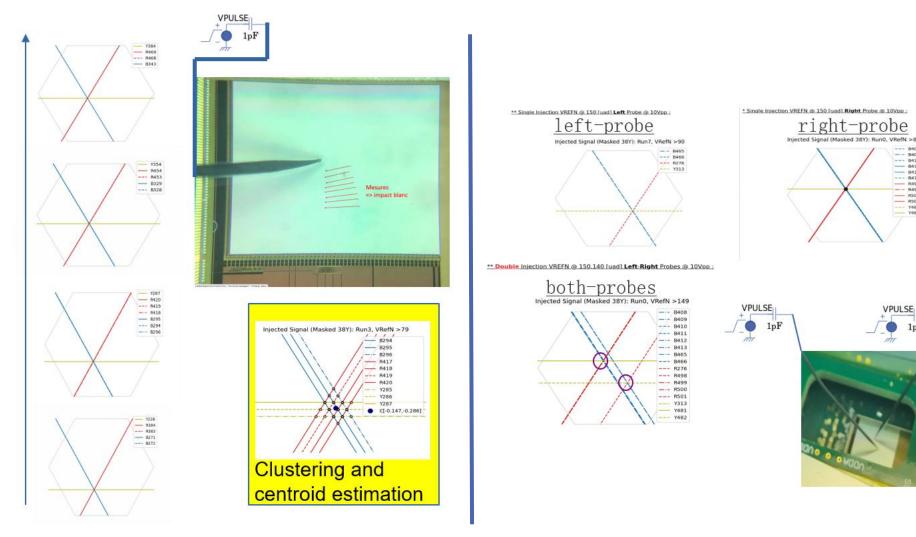
- Pedestal S-curve calibration
- A scan of all the DAC values was performed to find the best operational point
- ☐ Threshold spread as function of the global current parameter
- ☐ The adjustment of the 3-bit inner readout-cell local current source permits to adjust the 50% crossing of the S-curve





Position sensor test

☐ Test with direct injection of charges using probes

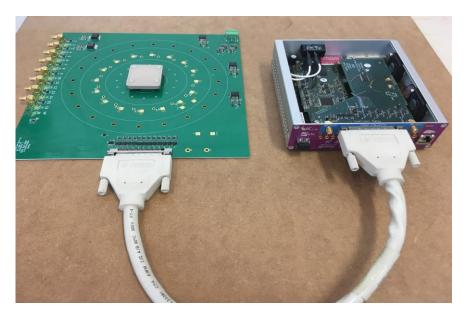


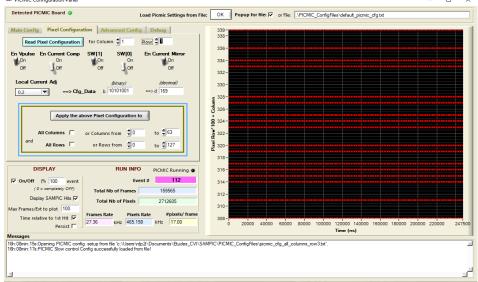
One probe injection

Two probes injection

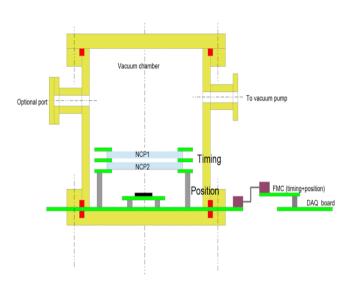
PICMIC DAQ

- ☐ With both time and position sensors tested, a dedicated DAQ board was developed
- ☐ Distribute the same clock (40 MHz) to both the timing and position chips
- ☐ Collect data from both and associate them
- ☐ The DAQ board was placed within the SAMPIC module.





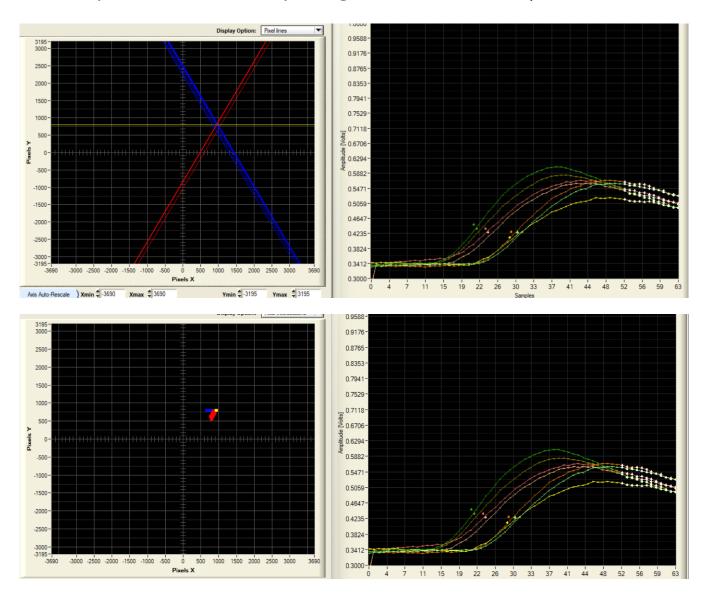
- ☐ The first prototype including:
 - Two 5-cm diameter MCP
 - ❖ A board hosting 16 timing sensors (only 8 were cabled)
 - ❖ A mezzanine hosting the pixel sensors
 - A Master board
- ☐ All are placed within a vacuum system (<10e-5 mB)



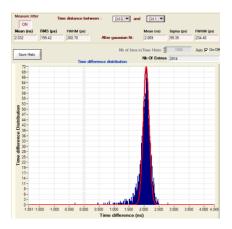


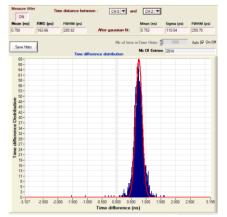


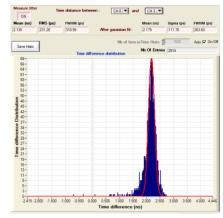
lacktriangle The whole system was tested by using collimated lpha and γ sources

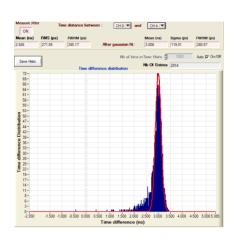


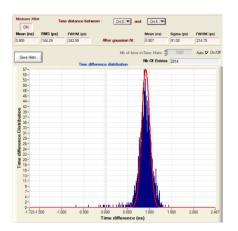
☐ Histograms of arrival time difference of Ch1,Ch2, Ch3, Ch4, Ch5, Ch6,Ch7 and Ch0

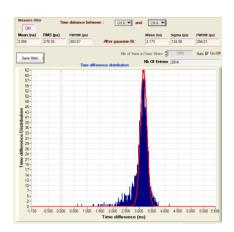


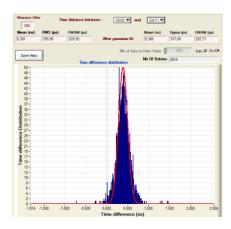












 $\sigma(T_i$ -T_j) is 100-120 ps

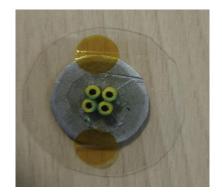


 σ_{abs} is around 25-30 ps

 \Box The whole system was tested by using collimated α and γ sources









0.5 mm holes

1 mm holes

RunData

Entries 216
Mean x 603.1
Std Dev y 1149

2000

1000

-1000

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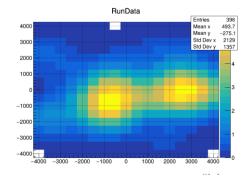
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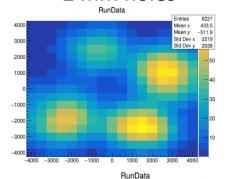
-4000

-40





2 mm holes



1000 0 -1000 -2000 -3000 -4000 -3000 -2000 -1000 0 1000 2000

4000

3000 -

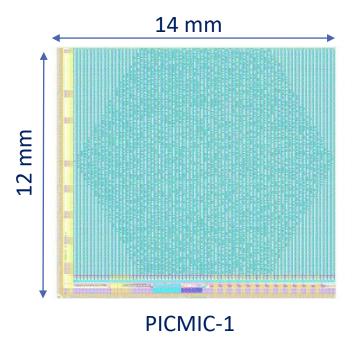
Many holes of 0.3mm diameter and 0.8 mm pitch

1000

-2000

Ongoing R&D: new position sensor PICMIC-1

- ☐ The PICMIC-0 chip was the first attempt to demonstrate the concept. PICMIC-1 was designed and improved on several features.
 - * Better calibration possibilities (8 bits DAC) to get better uniformity
 - \star Higher acquisition rate (1 MHz \rightarrow 10-30 MHz)
 - By reading out each column separately
 - ❖ By increasing the surface of the sensor by a factor of 4 (1.2 cm x 1.4 cm)
 - Adding a charge preamplifier to avoid current smearing problems for long tracks

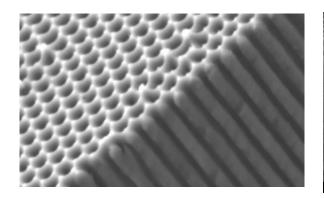


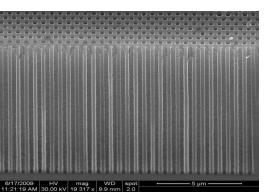
Ongoing R&D: PICMIC with Nano-Channel Plate (NCP)

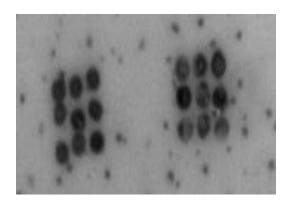
- ☐ A new kind of MCP that we call Nano-Chanel Plate (NCP) is being developed.
 - Small aperture (< 1 μm)
 - Large aspect ratio: L/d, ultra-fast response time
- ☐ It aims at producing structures with nanoholes that could be coated with emissive and resistive materials.

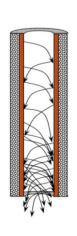


- Anodized Aluminium Oxide (AAO)
- Silicon electrochemical etching
- Femto-laser digging



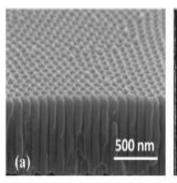


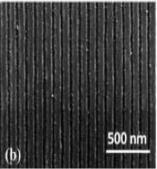


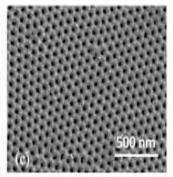


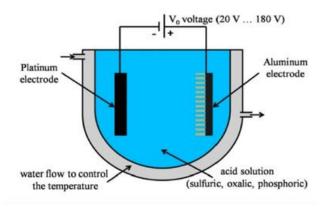
Ongoing R&D: AAO NCP

■ Nano Channel alumina structure made by electrolyte was invented twenty years ago: H. Masuda, K. Fukuda, Science 268, 1466 (1995)





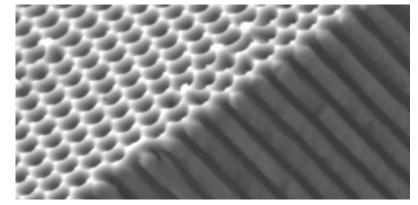




- \Box L/d = 200-300, L is the plate thickness and d the tube diameter. In principle we should have better timing than that of the MCP (less dispersion (TTS))
- ☐ Conic shape for higher quantum Efficiency is possible

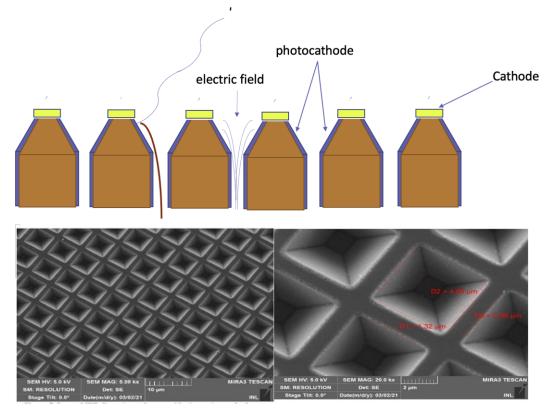
☐ New resistive and emissive coating materials are being studied to transform the

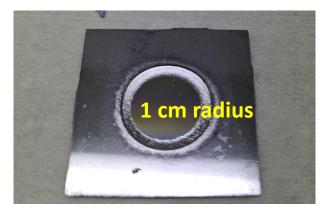
nanopore into NCP

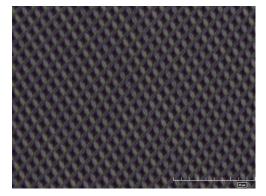


Ongoing R&D: Si NCP

- A highly granular reflective photocathode using silicon electrochemical etching is being developed. Photocathode is made of holes with conic shape.
 - Exploit the high spatial resolution the MCP offers
 - Increase the quantum efficiency
- ☐ The structure will be coated with different kinds of photocathode materials and then cast on MCP to test PICMIC as a photodetector concept.

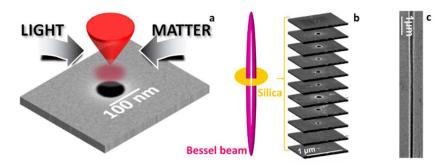




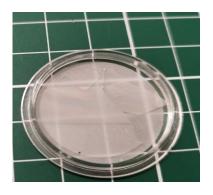


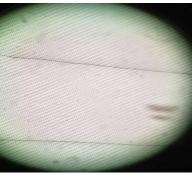
Ongoing R&D: Femto-Laser NCP

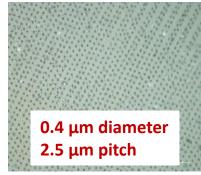
☐ The concept is to produce micro/nano-pore using the Femto-Laser techniques Bessel beam allows digging deep in transparent material producing regular pores



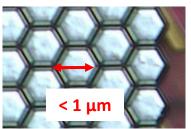
☐ By using lead-glass plates and obtaining high density of pores, one can not only produce NCP but also reduce the tedious chemical process used in MCP fabrication







- ☐ More precise time measurement with a dedicated ASIC
- ☐ Position sensor developed in smaller process like 65nm or less
 - More metal layers, less power consumption, high speed



Summary

□ The PICMIC concept that allows to simultaneously measure the time and position of MCP is validated
 □ Optimization and independent resolution measurements are ongoing
 □ High-rate capability with large surface position sensor has been designed
 □ New high granular reflective photocathode is being developed and will be soon tested

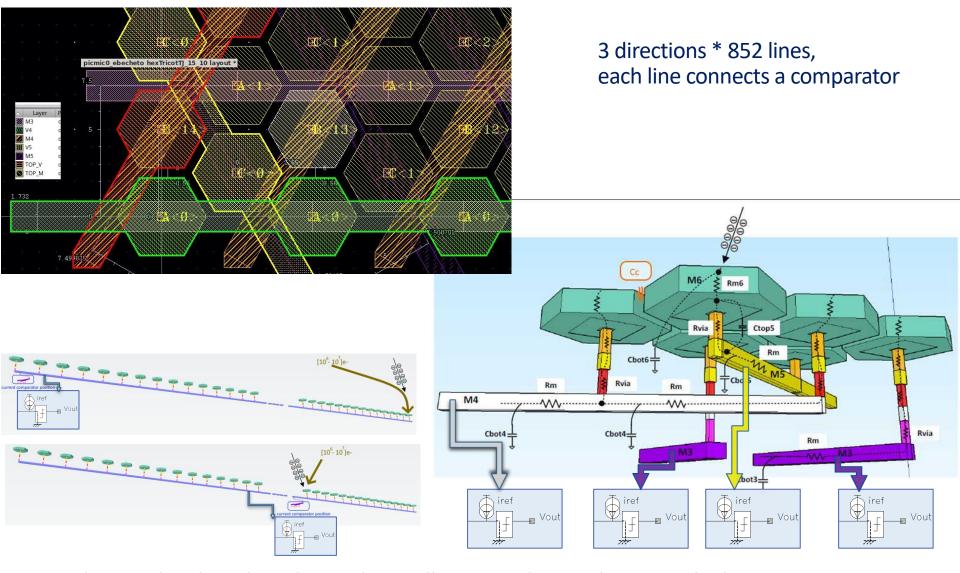
☐ A new generation called NCP with the aim to reach 1 ps and sub-micrometer

resolutions are being developed

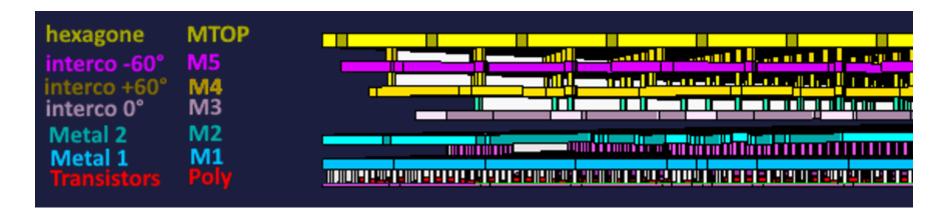
Thanks

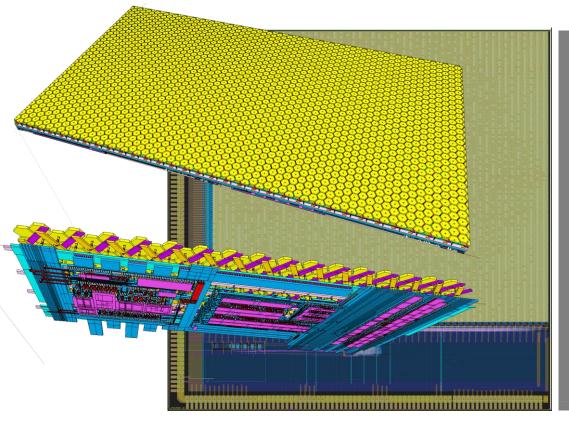
BACKUP

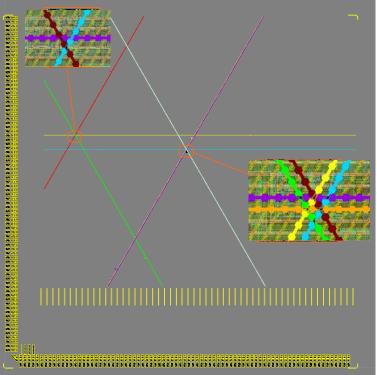
| | PICMIC-0 | PICMIC-1 |
|----------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------|-----------------------------------------------------------------------------------|
| Taille du circuit | 8.4 mm * 8.4 mm | 16.4 x 14.76 mm ² |
| Taille de la matrice de pixels Nb lignes(ROW) * nb colonnes(COL) Dimensions d'une cellule active Voies de lectures actives | 7.4 mm * 6.4 mm (0.5cm²) 128*53 140µm x 50µm 3*852=2556 canaux | 14.8 mm x 12.8 mm (1.9cm²) 184 x 74 199.92 um x 70 um 3*1704=5112 canaux |
| Puissance dissipée maximale | 256mA*1.8V ~ 0.5Watt | 2* 256 mA*1.8V ~ 1Watt |
| Charges incidentes [courant x temp] | [13uA x 2ns] et [1.8mA x 0.4ns] | [13uA x 2ns] et [1.8mA x 0.4ns] |
| Hit rate maximum | 16 cellules touchées pendant 400ns => 2.5MHz RATE | 25 MHz |
| Multiplicité | 8 pistes touchés par impact 2 impacts possible => 16 cellules | 2 piste/direction => 6 pistes 1 seul impact => 8 (+2 pour marge bruit) |
| Taille donnée d'une adresse touché | 7-bit pour ROW + 6-bit pour COL | 8-bit pour ROW + 7-bit pour COL (+ 2-bit augmentation taille x4) |
| Horloge de lecture interne | 40MHz par encodeur de priorité | 40MHz /colonne |
| Taille des données | 13-bit + Valid + Mrk | 15-bit + Valid + Mrk |
| Horloge de lecture externe | 40MHz sur 14-bit en parallèle 520 MBps | 8 liens 160MHz DDR (double data rate) SLVS or LVDS? 4.8GBps |
| Pitch (pas de quantification spacial) | 5μm (hauteur d'un hexagone) | 5µm |
| Nombre total d'hexagones | 2 077 200 (~2 Million) | 8 millions de pixels |



Depending on the algorithm, the readout-cell is somewhere in-between the line Depending on the position of the shower impact, the discriminator could be at strong opposite

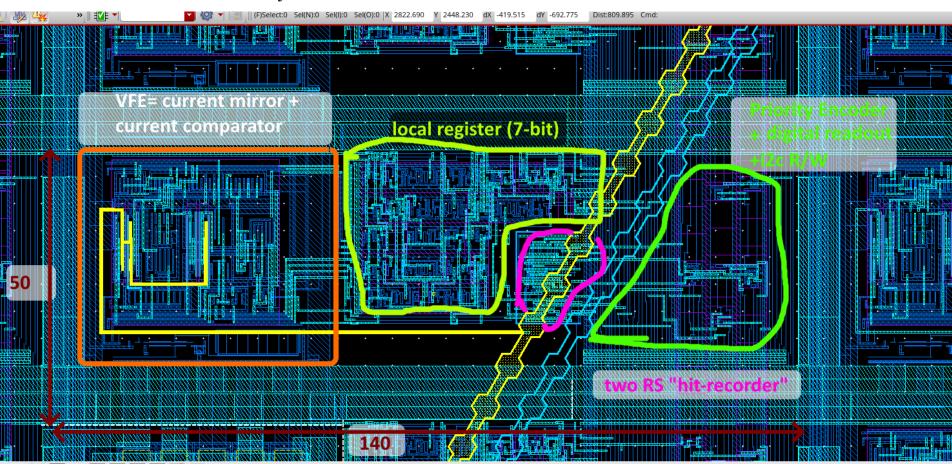




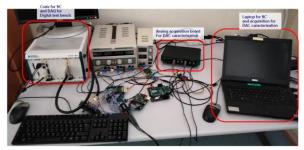


Layout of readout cell

Layout of readout-cell with M1 and M2: 140u x 50u

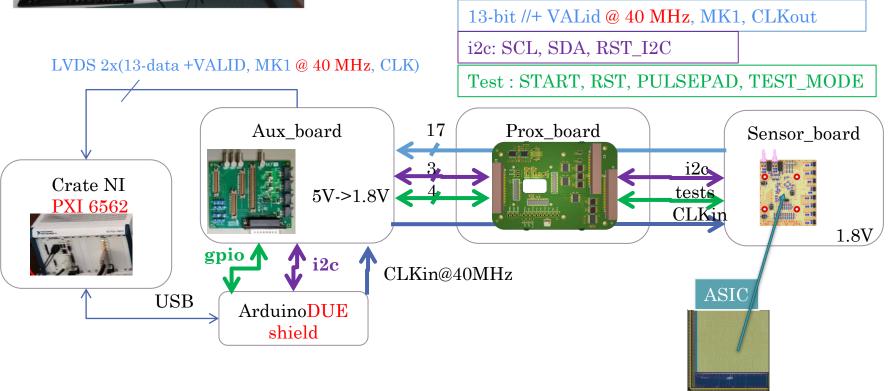


PICMICO DAQ

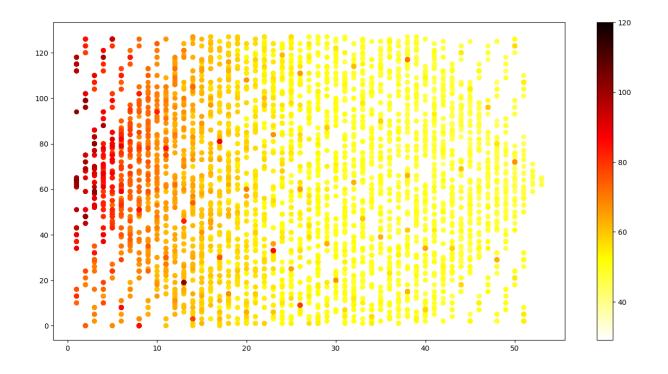


Test bench HW developped by IPHC

- New design for sensor board & Arduino shield
- Most of test bench HW **reused** from a previous project
- I2C: Arduino DUE board
- DAQ : NI PXI6562 board 16 I/O up to 200 MHz



<u>Unwanted</u> effect observed : threshold spread in the current comparator reference, due to IR-drop in the matrice <u>before</u> calibration. Threshold varies from $40\mu A$ to $120\mu A$



Also 38 channel are noisy due to coupling between the memory Flush signal in Metal 2 with a few horizontal Metal 3 lines